

Electronic Patent Application Fee Transmittal

Application Number:	10570668			
Filing Date:	06-Mar-2006			
Title of Invention:	SOI WAFER AND ITS MANUFACTURING METHOD			
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Filer:	Sean Christophe Myers-Payne/Son T. Nguyen			
Attorney Docket Number:	P29124			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	540	540
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
Total in USD (\$)				1650